MOSFETs Silicon N-Channel MOS (U-MOSVII)

# **TPC8074**

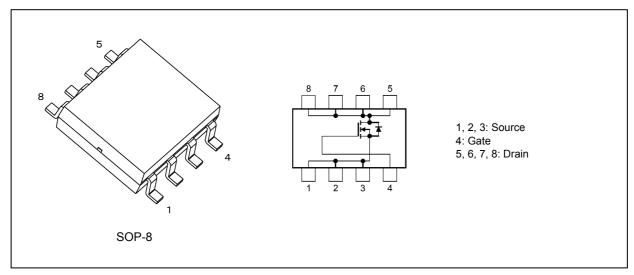
#### 1. Applications

- Lithium-Ion Secondary Batteries
- Power Management Switches
- Notebook PCs

#### 2. Features

- (1) Small footprint due to a small and thin package
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 5.1 \text{ m}\Omega \text{ (typ.)} (V_{GS} = 10 \text{ V})$
- (3) Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- (4) Enhancement mode:  $V_{th}$  = 1.3 to 2.3 V (V\_{DS} = 10 V,  $I_{D}$  = 0.2 mA)

#### 3. Packaging and Internal Circuit



### 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristics				Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	30	V
Gate-source voltage			V <sub>GSS</sub>	±20	
Drain current (DC)		(Note 1)	Ι <sub>D</sub>	17	A
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	68	
Power dissipation	(t = 10 s)	(Note 2)	PD	1.9	W
Power dissipation	(t = 10 s)	(Note 3)	PD	1.0	W
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	75	mJ
Avalanche current			I <sub>AR</sub>	17	A
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

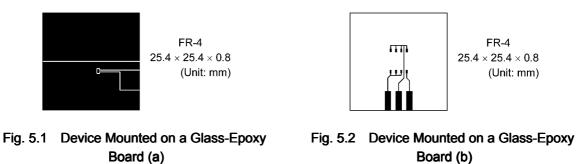
Characteristi	cs		Symbol	Max	Unit
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	65.7	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V\_{DD} = 24 V, T\_{ch} = 25°C (initial), L = 0.2 mH, R\_G = 1  $\Omega$ , I\_{AR} = 17 A



Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

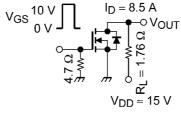
### 6. Electrical Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

### 6.1. Static Characteristics

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V		_	±0.1	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V		_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30		_	V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	15	_	_	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.2 mA	1.3	_	2.3	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 8.5 A		6.7	8.7	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8.5 A		5.1	6.5	

### 6.2. Dynamic Characteristics

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1800	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	88	—	
Output capacitance	C <sub>oss</sub>		_	330	_	
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1.	_	3.1	_	ns
Switching time (turn-on time)	t <sub>on</sub>			10	_	
Switching time (fall time)	t <sub>f</sub>			7.2	_	
Switching time (turn-off time)	t <sub>off</sub>		_	39	_	



Duty  $\leq$  1%,  $t_W$  = 10  $\mu s$ 

#### Fig. 6.2.1 Switching Time Test Circuit

### 6.3. Gate Charge Characteristics

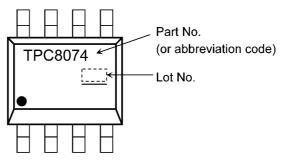
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 24$ V, $V_{GS}$ = 10 V, $I_D$ = 17 A	—	25	—	nC
Gate-source charge 1	Q <sub>gs1</sub>	]	_	5.7	_	
Gate-drain charge	Q <sub>gd</sub>			2.8	_	

### 6.4. Source-Drain Characteristics

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Pulsed reverse drain current (Note	5) I <sub>DRP</sub>	—	_	—	68	A
Diode forward voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 17 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

Note 5: Ensure that the channel temperature does not exceed 150°C.

### 7. Marking (Note)



#### Fig. 7.1 Marking

 Note:
 A line under a Lot No. identifies the indication of product Labels.

 Not underlined: [[Pb]]/INCLUDES > MCV

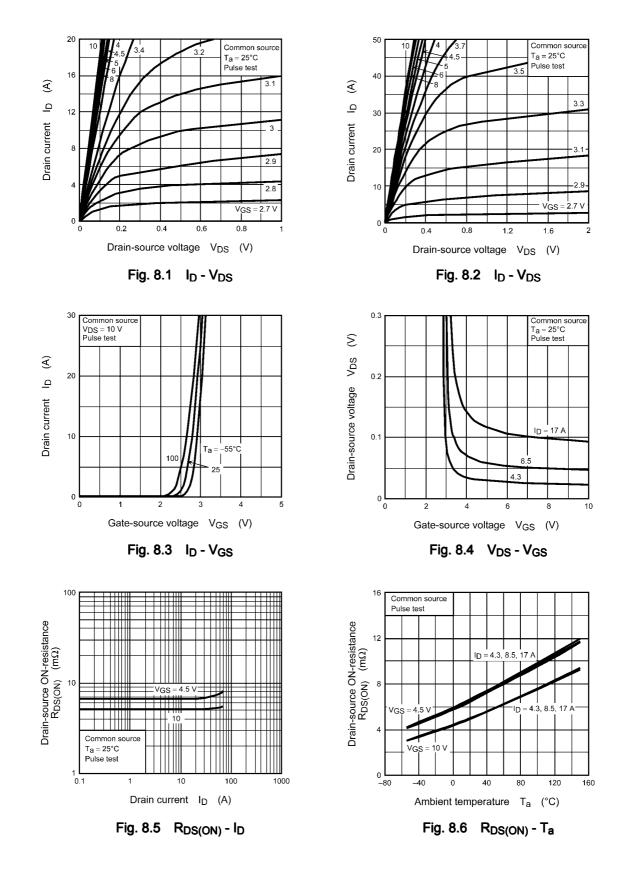
 Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

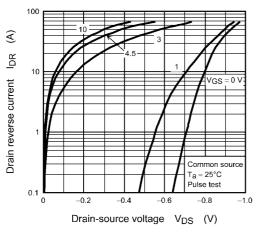
 Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

 The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on

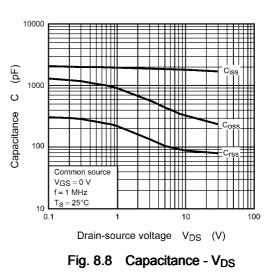
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# 8. Characteristics Curves (Note)









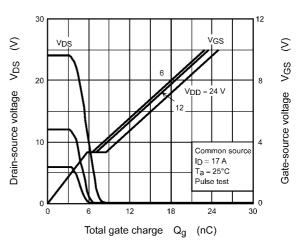


Fig. 8.10 Dynamic Input/Output Characteristics

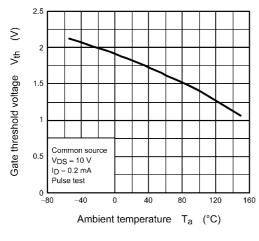
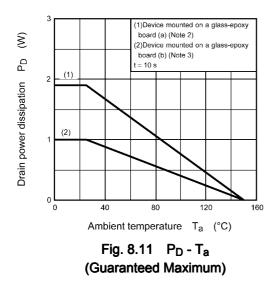
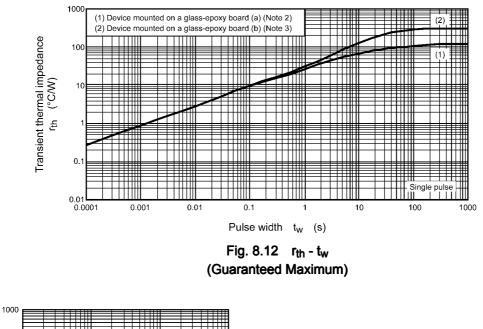


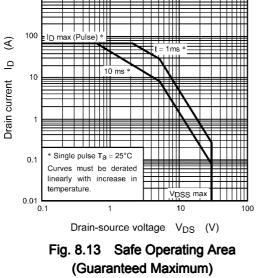
Fig. 8.9 Vth - Ta











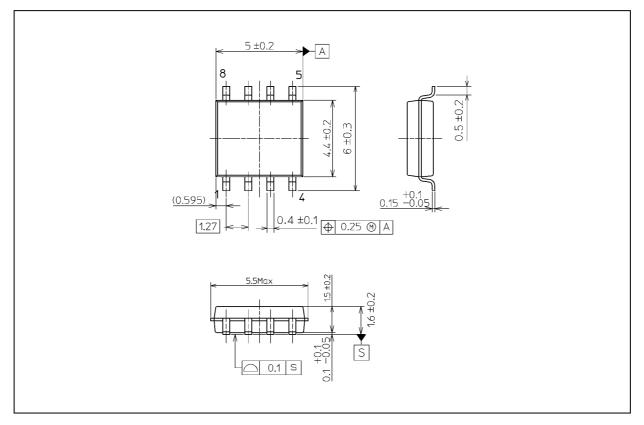
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



# TPC8074

### Package Dimensions

Unit: mm



Weight: 0.085 g (typ.)

	Package Name(s)
TOSHIBA: 2-6J1S	
Nickname: SOP-8	

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